

SOT1075-1

plastic low profile fine-pitch ball grid array package; 49 balls

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	LFBGA49
Package type industry code	LFBGA49
Package style descriptive code	LFBGA (low profile fine-pitch ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	---
Mounting method type	S (surface mount)
Issue date	17-3-2008

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		3.9	-	4	4.1	mm
E	package width		3.9	-	4	4.1	mm
A	seated height		1.05	-	1.15	1.25	mm
A ₂	package height		0.85	-	0.9	0.95	mm
n ₂	actual quantity of termination		-	-	49	-	



2. Package outline

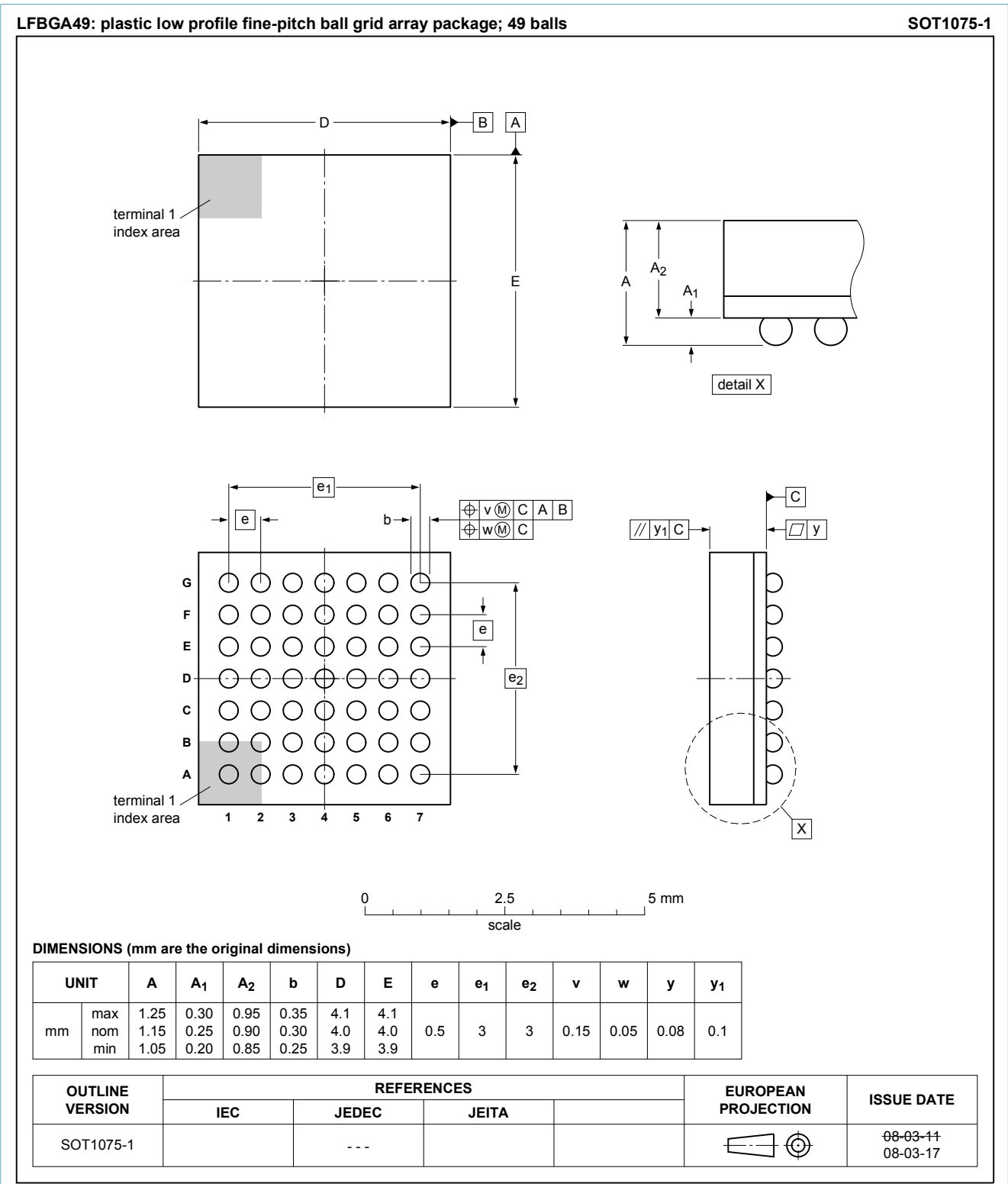


Fig. 1. Package outline LFBGA49 (SOT1075-1)

3. Soldering

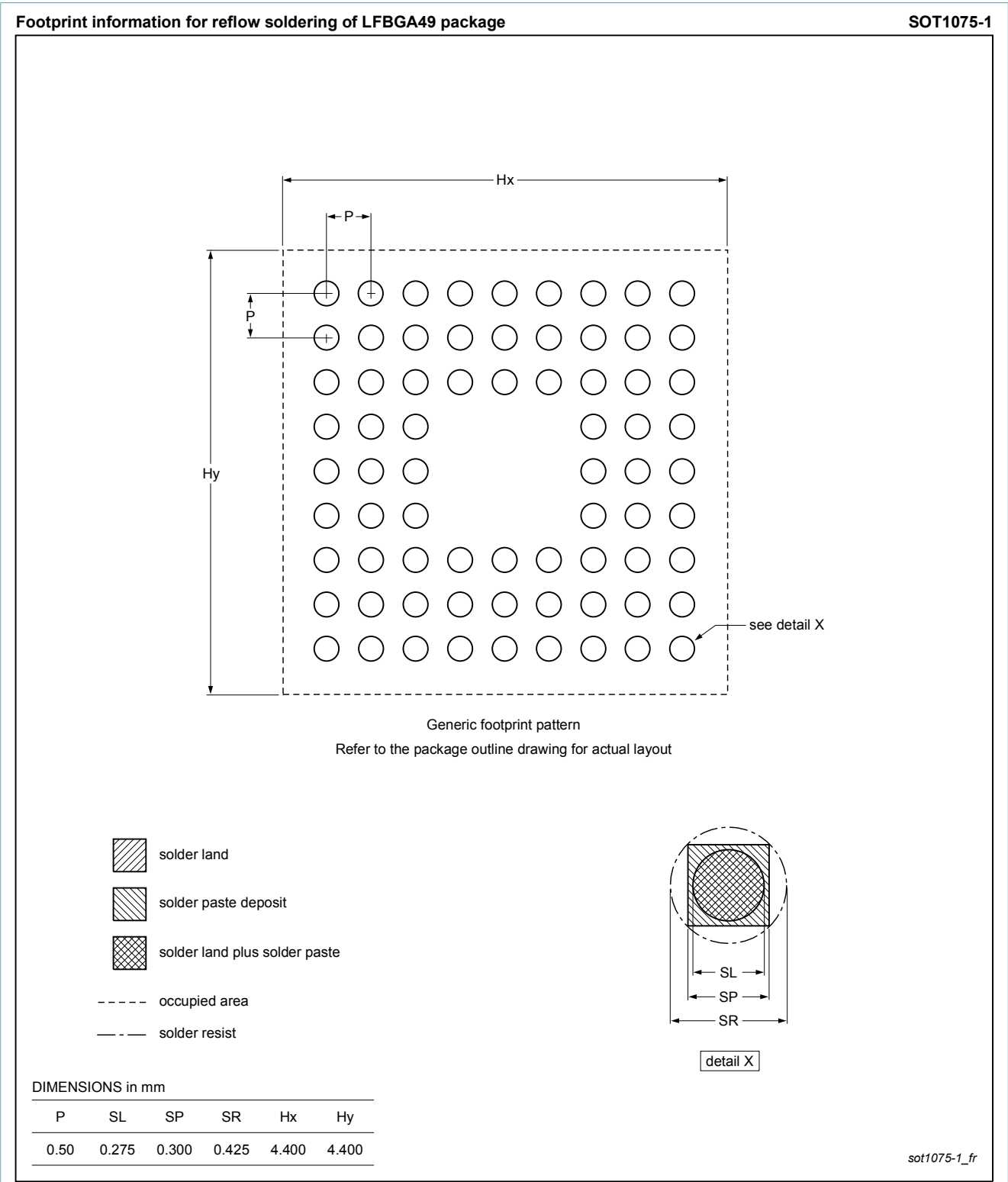


Fig. 2. Reflow soldering footprint for LFBGA49 (SOT1075-1)

4. Legal information

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